

HD74HC108

Dual J-K Flip-Flops

(with Preset, Common Clear and Common Clock)

REJ03D0560-0200 (Previous ADE-205-433) Rev.2.00 Oct 11, 2005

Description

This flip-flop is edge sensitive to the clock input and change state on the negative transition of the clock pulse. Each flip-flop has independent J, K, and preset inputs and Q and Q outputs. Two flip-flops are controlled by a common clear and a common clock. Preset and clear are independent of the clock and accomplished by a low logic level on the corresponding input.

Features

• High Speed Operation: t_{pd} (Clock to Q) = 20 ns typ (C_L = 50 pF)

• High Output Current: Fanout of 10 LSTTL Loads

• Wide Operating Voltage: $V_{CC} = 2 \text{ to } 6 \text{ V}$

• Low Input Current: 1 μA max

• Low Quiescent Supply Current: I_{CC} (static) = 2 μ A max (Ta = 25°C)

• Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74HC108RPEL	SOP-14 pin (JEDEC)	PRSP0014DE-A (FP-14DNV)	RP	EL (2,500 pcs/reel)

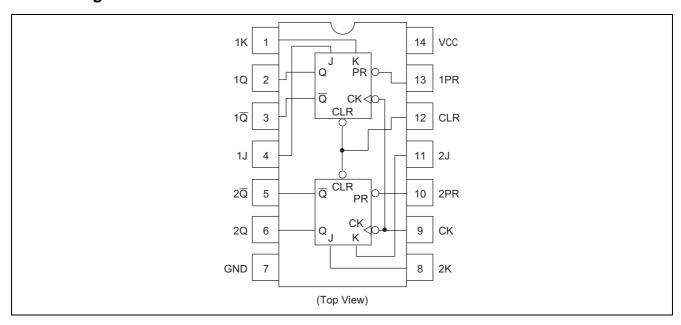
Function Table

		Out	puts				
Preset	Clear	Clock	J	K	Q	Q	
L	Н	Х	Х	Х	Н	L	
Н	L	Х	Х	X	L	Н	
L	L	Х	Х	Х	H* ¹	H* ¹	
Н	Н		L	L	No change		
Н	Н		L	Н	L	Н	
Н	Н		Н	L	Н	L	
Н	Н		Н	Н	Toggle		
Н	Н	L	Х	Х	No change		
Н	Н	Н	Х	Х	No change		
Н	Н		Х	Х	No ch	nange	

Note: 1. Q and \overline{Q} will remain High as long as preset and Clear are Low, but Q and \overline{Q} are unpredictable, if Preset and Clear go High simultaneously.

H: High levelL: Low levelX: Irrelevant

Pin Arrangement



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage range	Vcc	-0.5 to 7.0	V
Input / Output voltage	Vin, Vout	-0.5 to V _{CC} +0.5	V
Input / Output diode current	I _{IK} , I _{OK}	±20	mA
Output current	I ₀	±25	mA
V _{CC} , GND current	I _{CC} or I _{GND}	±50	mA
Power dissipation	P _T	500	mW
Storage temperature	Tstg	-65 to +150	°C

Note: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

Recommended Operating Conditions

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V _{CC}	2 to 6	V	
Input / Output voltage	V _{IN} , V _{OUT}	0 to V _{CC}	V	
Operating temperature	Та	-40 to 85	°C	
Input rise / fall time*1		0 to 1000		V _{CC} = 2.0 V
	t _r , t _f	0 to 500	ns	$V_{CC} = 4.5 \text{ V}$
		0 to 400		$V_{CC} = 6.0 \text{ V}$

Note: 1. This item guarantees maximum limit when one input switches.

Waveform: Refer to test circuit of switching characteristics.

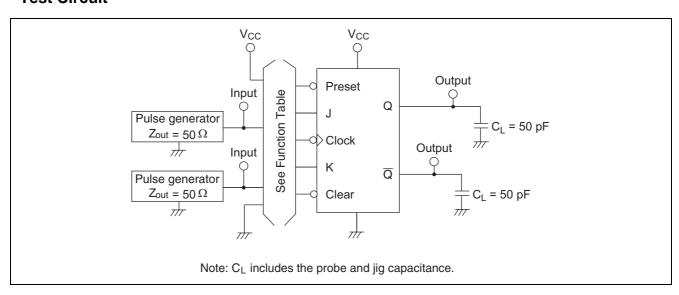
Electrical Characteristics

			Т	a = 25°	С	Ta = -40 to+85°C				
Item	Symbol	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit	Test Cor	nditions
Input voltage	V_{IH}	2.0	1.5	_	_	1.5	_	V		
		4.5	3.15	_	_	3.15	_			
		6.0	4.2	_	_	4.2	_			
	V_{IL}	2.0	_	_	0.5	_	0.5	V		
		4.5	_	_	1.35	_	1.35			
		6.0	_	_	1.8	_	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	_	1.9	_	V	$Vin = V_{IH} or V_{IL}$	$I_{OH} = -20 \mu A$
		4.5	4.4	4.5	_	4.4	_			
		6.0	5.9	6.0	_	5.9	_			
		4.5	4.18	_	_	4.13	_			$I_{OH} = -4 \text{ mA}$
		6.0	5.68	_	_	5.63	_			$I_{OH} = -5.2 \text{ mA}$
	V _{OL}	2.0	_	0.0	0.1	_	0.1	V	$Vin = V_{IH} or V_{IL}$	$I_{OL} = 20 \mu A$
		4.5	_	0.0	0.1	_	0.1			
		6.0	_	0.0	0.1	_	0.1			
		4.5	_	_	0.26	_	0.33			I _{OL} = 4 mA
		6.0	_	_	0.26	_	0.33			I _{OL} = 5.2 mA
Input current	lin	6.0		_	±0.1	_	±1.0	μΑ	Vin = V _{CC} or GND	
Quiescent supply current	Icc	6.0	_	_	2.0	_	20	μА	$Vin = V_{CC}$ or GN	D, lout = $0 \mu A$

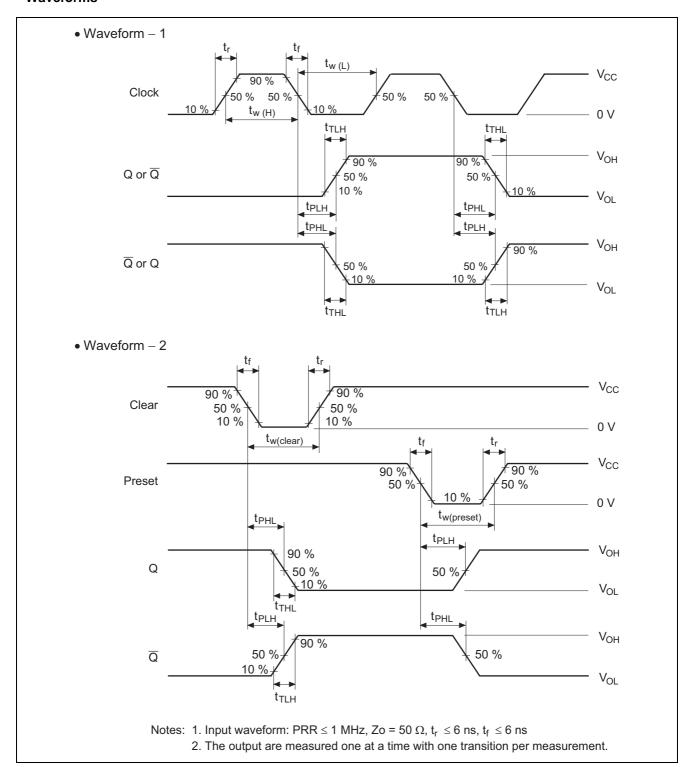
Switching Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

			Т	Ta = 25°C Ta = -40 to +85°C		to +85°C			
Item	Symbol	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions
Maximum clock	f _{max}	2.0	_	_	6	_	5	MHz	
frequency		4.5	_	_	30	_	24		
		6.0	_	_	35	_	28		
Propagation delay	t _{PLH} , t _{PHL}	2.0	_	_	150	_	190	ns	Clock to Q or Q
time		4.5	_	20	30	_	38		
		6.0	_	_	26	_	33		
		2.0	_	_	140	_	175	ns	Clear to Q or Q
		4.5	_	18	28	_	35		
		6.0	_	_	24	_	30		
		2.0	_	_	140	_	175	ns	Preset to Q or Q
		4.5	_	16	28	_	35		
		6.0	_	_	24	_	30		
Pulse width	t _w	2.0	80	_	_	100	_	ns	
		4.5	16	7	_	20	_		
		6.0	14	_	_	17	_		
Setup time	t _{su}	2.0	100	_	_	125	_	ns	
		4.5	20	2	_	25	_		
		6.0	17	_	_	21	_		
Hold time	t _h	2.0	5	_	_	5	_	ns	
		4.5	5	-1	_	5	_		
		6.0	5	_	_	5	_		
Removal time	t _{rem}	2.0	100	_	125	_	_	ns	
		4.5	20	-2	25	_	_	1	
		6.0	17	_	21	_	_	1	
Output rise/fall	t _{TLH} , t _{THL}	2.0	_	_	75	_	95	ns	
time		4.5	_	5	15	_	19	1	
		6.0	_	_	13	_	16		
Input capacitance	Cin	_	_	5	10	_	10	pF	

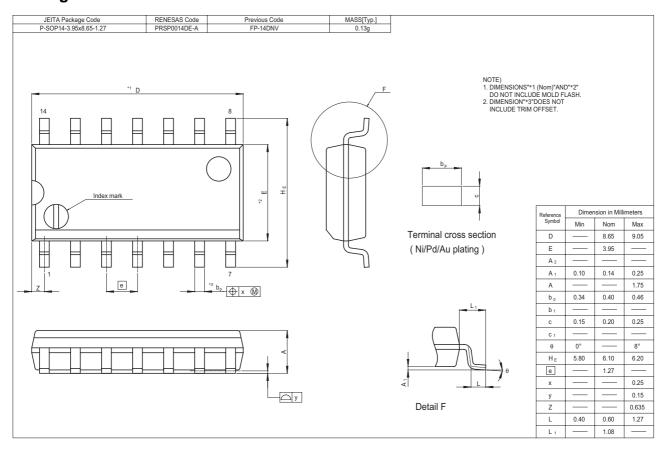
Test Circuit



Waveforms



Package Dimensions



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